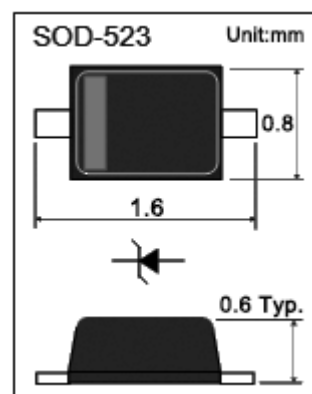


- ◇ Fast switching devices
- ◇ **SOD523** Micro SMD package
- ◇ RoHS compliant / Green EMC
- ◇ Matte Tin (Sn) Lead finish
- ◇ Cathode Band / Device marking
- ◇ Surface Mount Package Ideally Suited for Automatic Insertion
- ◇ For General Purpose Switching Applications
- ◇ High Conductance



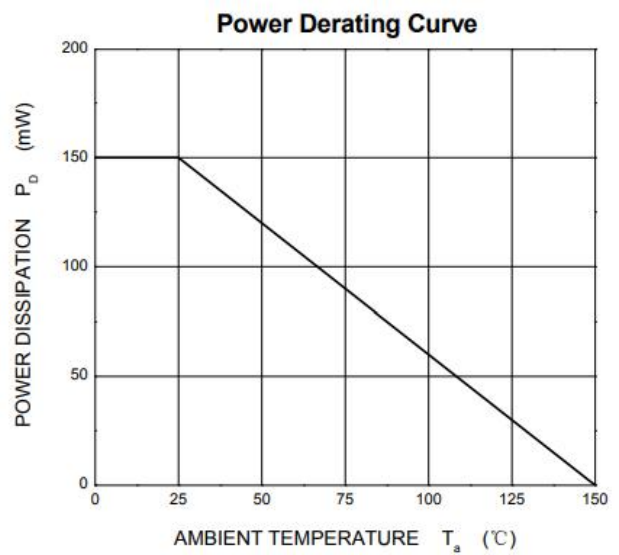
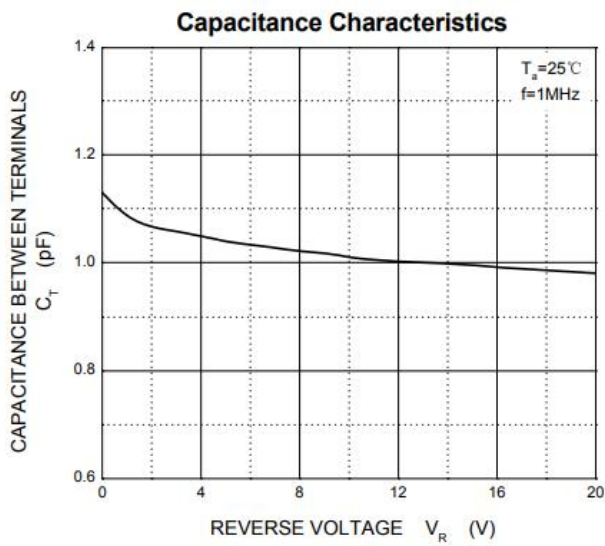
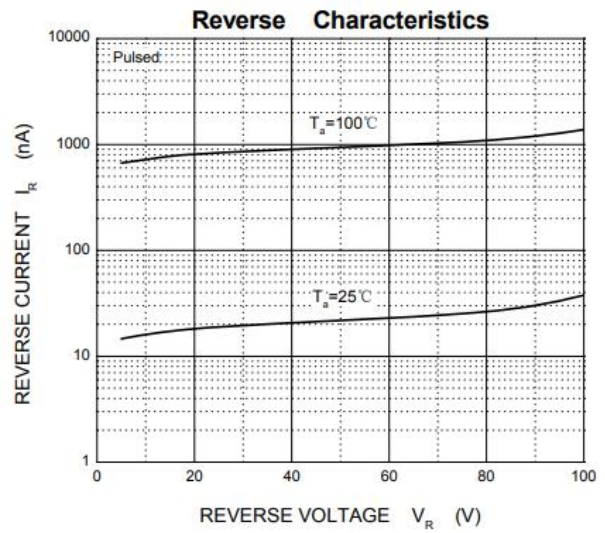
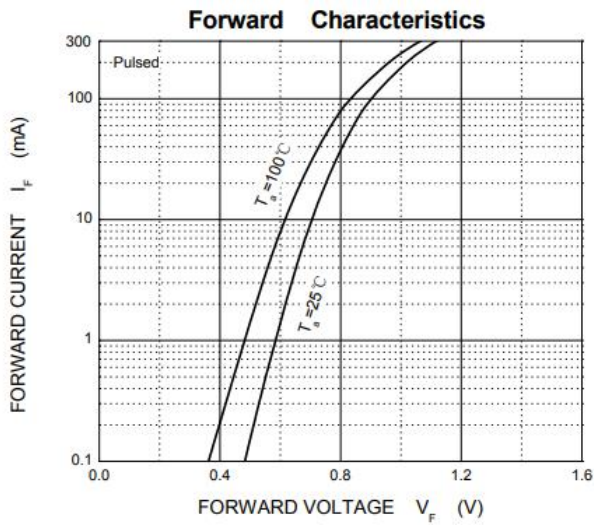
Maximum Ratings (Ta = 25 °C)

Symbol	Parameter	Value	Units
V_{RM}	Non-Repetitive Peak Reverse Voltage	100	V
V_{RRM}	Repetitive Peak Reverse Voltage	75	V
$V_{R(RMS)}$	RMS Reverse Voltage	53	V
I_{FM}	Forward Continuous Current	300	mA
I_O	Average Rectified Output Current	150	mA
I_{FSM}	Non-Repetitive Peak Forward Surge Current (@t=8..3ms)	2.0	A
P_D	Power Dissipation	150	mW
T_J	Junction Temperature	150	°C
T_{STG}	Storage Temperature	-55 to +150	°C

Electrical Characteristics (Ta = 25 °C)

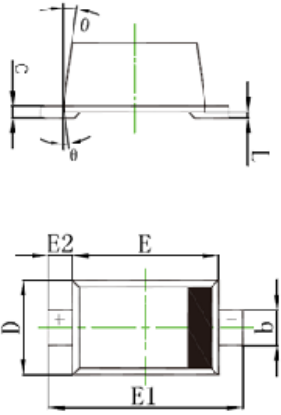
Symbol	Parameter	Conditions	Min	Max	Units
V_F	Forward Voltage	$I_F = 1mA$		0.715	V
		$I_F = 10mA$		0.855	V
		$I_F = 50mA$		1.0	V
		$I_F = 150mA$		1.25	V
I_R	Reverse current	$V_R = 75V$ (25°C)		1	μA
		$V_R = 20V$ (25°C)		25	nA
		$V_R = 75V$ (150°C)		50	μA
C_T	Capacitance	$V_R = 0V, f = 1MHz$		2	pF
t_{rr}	Reverse Recovery Time	$I_F = I_R = 10mA,$ $I_{RR} = 1mA, R_L = 100\Omega$		4	ns

Typical Characteristics



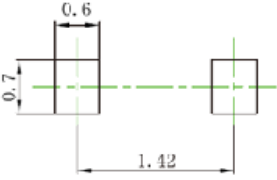
Package Dimensions

Package outline : SOD-523



Unit	A	A1	b	c	D	E	E1	E2	L	θ
Max.	0.77	0.70	0.35	0.15	0.85	1.30	1.70	0.20	0.07	7°
Min.	0.51	0.50	0.25	0.08	0.75	1.10	1.50	REF.	0.01	REF.

SOD523 Package Outline



End Pattern Recommendation

Note:

1. Halogen free,EMC
2. Pb free solder
3. Lead thickness includes solder plating
4. Lead frame: Cu
5. Other Tolerance: ± 0.05
6. Dimensions are exclusive of Burrs,Mold Flash and Tie Bar extrusions
7. Unit: mm